

Financial Results of FY2020 Third-Quarter

From April 1, 2020 to December 31, 2020



**Brightening the Future
Since 1946**

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Financial Results Overview of FY2020 Third-Quarter (consolidated)

Financial Results

(Billions of yen)

	FY2019 9 months* ¹ (Result)	FY2020 9 months* ¹ (Result)	YoY	
			Amount	Ratio of Change
Net Sales	107.5	135.5	+28.0	+26%
Operating Profit (Ratio against Net Sales)	0.1 (0%)	14.9 (11%)	+14.8	—
Ordinary Profit (Ratio against Net Sales)	1.2 (1%)	16.1 (12%)	+14.9	—
Profit* ² (Ratio against Net Sales)	0.1 (0%)	10.9 (8%)	+10.9	—

* 1 From April 1, 2020 to December 31, 2020

* 2 Profit attributable to owners of parent

Earnings per Share	0.48yen	80.97yen
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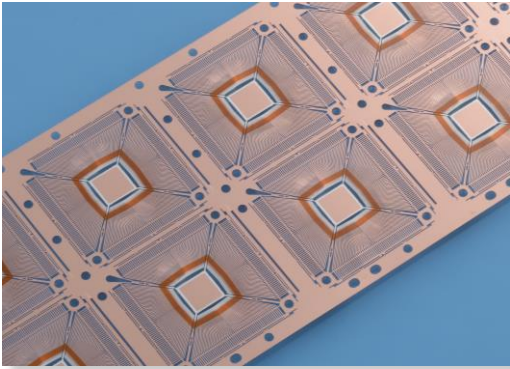
Net sales :

- The demand of automobiles and smartphones declined by spreading of COVID-19. Nevertheless, due to a large increase of sales of flip-chip type packages for servers for data centers and PCs supported by the expansion of teleworking and online learning and the practical implementation of the fifth-generation mobile communications systems (5G), expanding orders of ceramic electrostatic chucks for semiconductor manufacturing equipment, and recovery in sales of leadframes in the third-quarter, net sales increased 26% year on year.

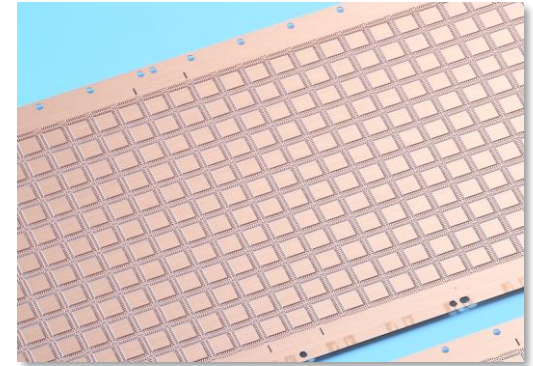
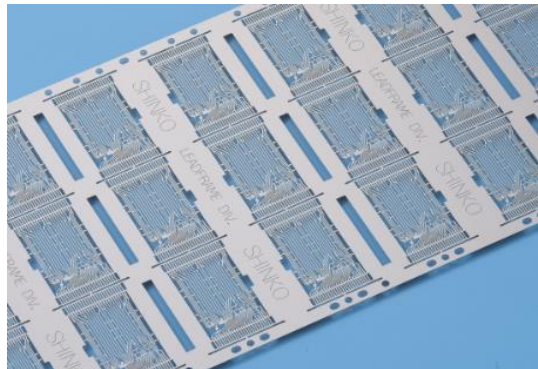
Profit :

- Profit increased greatly thanks to improving profitability by the growth in sales mainly from high-value-added products.

IC Leadframes



Stamped Leadframes



**Etched Leadframes
(QFN-Type)**

【Applications】

**Smartphones, Automobiles, PCs, Home applications,
Industrial equipment, etc.**

IC Leadframes (Consolidated)

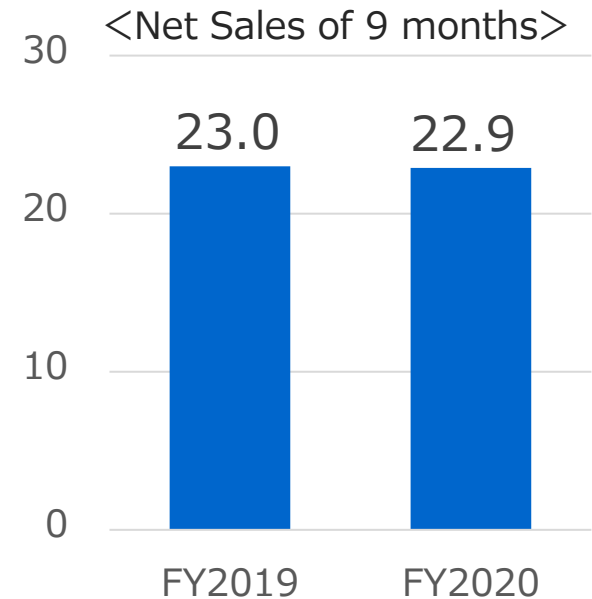
(Billions of yen)

	FY2019 9 months* ¹ (Result)	FY2020 9 months* ¹ (Result)	YoY		FY2019 Total (Result)
			Amount	Ratio of Change	
Net Sales of IC Leadframes	23.0 [21%]* ²	22.9 [17%]* ²	-0.1	-0%	31.2

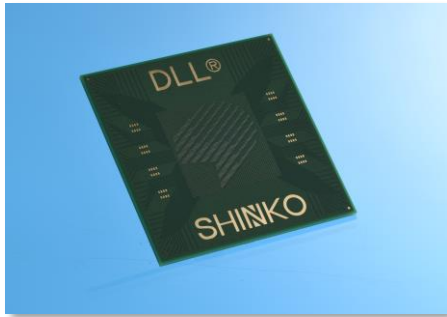
* 1 From April 1, 2020 to December 31, 2020 * 2 Represent % of Net Sales

● Leadframes:

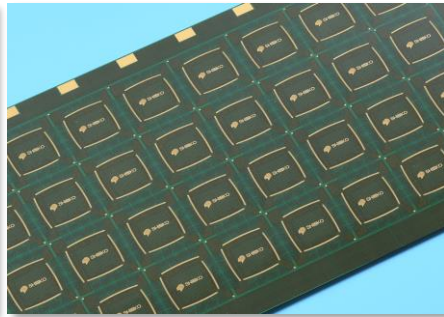
Since demand of QFN-type leadframes expanded for a wide range of applications, and demand for automobiles bottomed out in the third-quarter, sales of leadframes turn to recover.



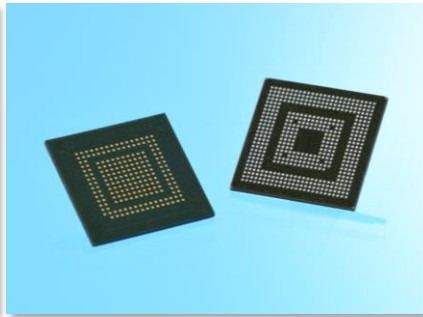
IC Packages



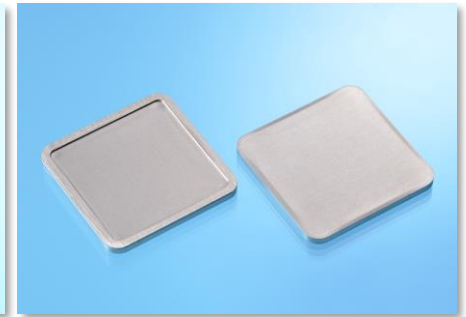
Flip-Chip Type Packages



Plastic BGA Substrates



IC Assemblies



Heat Spreaders

【Applications】

PCs, Servers, Smartphones, Consumer Products, etc.

IC Packages (Consolidated)

(Billions of yen)

	FY2019 9 months* ¹ (Result)	FY2020 9 months* ¹ (Result)	YoY		FY2019 Total (Result)
			Amount	Ratio of Change	
Net Sales of IC Packages	66.6 [62%]* ²	89.8 [66%]* ²	+23.3	+35%	92.4

* 1 From April 1, 2020 to December 31, 2020 * 2 Represent % of Net Sales

● Flip-Chip Type Packages:

Demand expanded significantly for servers and PCs, and the new production lines in Takaoka plant which has been made large capital investment began mass operation from October in 2020 helped sales increase.

● Plastic BGA Substrates:

Orders greatly increased for advanced memory due to commence operation of the new production lines.

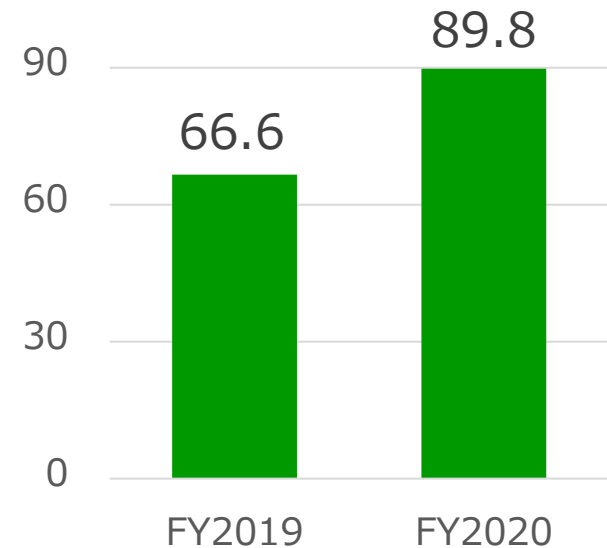
● IC Assemblies:

Sales increased because of demand expanded for high-end smartphones.

● Heat Spreaders for CPUs:

Sales remained in good shape for servers.

<Net Sales of 9 months>



Hermetic Seal Parts



**Ceramic Electrostatic
Chuck**



**Glass-to-Metal Seals for
Optical Devices**



**Glass-to-Metal Seals for
Optical Communication
Equipment**

【Applications】

**Semiconductor Manufacturing Equipment, Automobiles,
Consumer Products, Communications Equipment, etc.**

Hermetic Seal Parts (Consolidated)

(Billions of yen)

	FY2019 9 months* ¹ (Result)	FY2020 9 months* ¹ (Result)	YoY		FY2019 Total (Result)
			Amount	Ratio of Change	
Net Sales of Hermetic Seal Parts	17.3 [16%]* ²	22.6 [17%]* ²	+5.3	+31%	24.0

* 1 From April 1, 2020 to December 31, 2020 * 2 Represent % of Net Sales

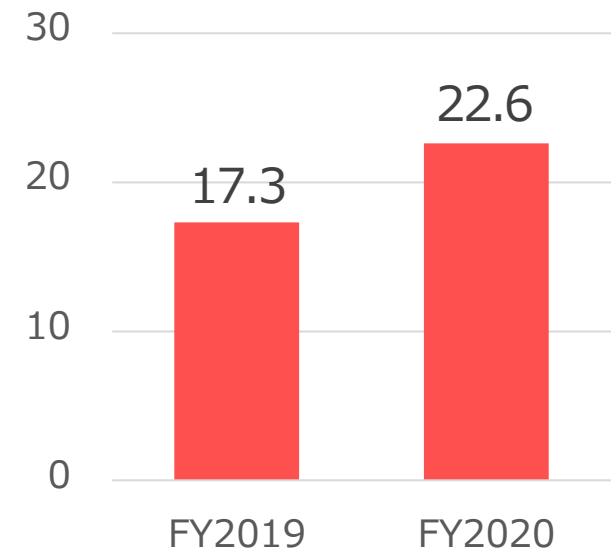
- Ceramic Electrostatic Chucks:**

Sales increased greatly due to an ongoing lager-order environment.

- Glass-to-Metal Seals:**

Sales remained low for optical communication equipment despite it showed a recovery trend in the third-quarter. As a result, revenue decreased.

<Net Sales of 9 months>



Revised Forecast of FY2020 (Announcement on January 28, 2021) (Billions of yen)

	FY2020			
	Previous Forecast: As of October 27, 2020	Current Forecast: As of January 28, 2021	vs. Previous Forecast	
			Amount	Ratio of Change
Net Sales	177.3	182.9	+5.6	+3%
Operating Profit	13.5	18.7	+5.2	+39%
Ordinary Profit	14.7	20.0	+5.3	+36%
Profit*	10.0	13.4	+3.4	+34%
Earnings per Share	74.02yen	99.19yen	—	—

* Profit attributable to owners of parent

Reasons for the revision of FY2020

- Orders of flip-chip type packages for servers and PCs are expected to remain high due to an upsurge in teleworking and online learning and the launch of 5G, and the production lines for flip-chip type packages which have been made large capital investments commenced operation will help sales increase.
- Sales of ceramic electrostatic chucks increased due to large demand in semiconductor manufacturing equipment market.
- Since demand for automobiles bottomed out in the third-quarter, sales of leadframes are expected to turn to recover.
- With these reasons, sales and profits are exceeding the forecast especially profits are progressing beyond expectations thanks to increased profitability by increasing sales of high-value-added products and so on.
- As semiconductor market will be steady performance remain good shape in the fourth-quarter in FY 2020, it is anticipated for order situation to remain good shape. Given these factors, we have revised the forecast of FY2020 released on October 27, 2020.
- We have revised the exchange rate which is the prerequisites for the forecast by changing exchange rate from 102yen per dollar to 100yen per dollar.

Forecast of FY2020 (consolidated)



Sales/Profit/Cash Dividend

(Billions of yen)

	FY2019 (Result)			FY2020 *1 (1st-Half Result · 2nd-Half Forecast)			YoY	
	1st Half	2nd Half	FY 2019	1st Half*2	2nd Half	FY 2020	Amount	Ratio of Change
Net Sales	69.3	79.1	148.3	84.5	98.4	182.9	+34.6	+23%
Operating Profit (Ratio against Net Sales)	-1.0 (-1%)	4.2 (5%)	3.2 (2%)	7.2 (9%)	11.5 (12%)	18.7 (10%)	+15.5	+479%
Ordinary Profit (Ratio against Net Sales)	-0.5 (-1%)	5.3 (7%)	4.8 (3%)	8.3 (10%)	11.7 (12%)	20.0 (11%)	+15.2	+316%
Profit*3 (Ratio against Net Sales)	-1.0 (-1%)	3.7 (5%)	2.7 (2%)	5.6 (7%)	7.8 (8%)	13.4 (7%)	+10.7	+398%

Exchange Rates (Yen/US dollar)	107	FY2020 1Q-3Q (Result) 104	FY2020 4Q (Assumption) 100
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*1 As of January 28, 2021

*2 Results of FY2020 1st-Half

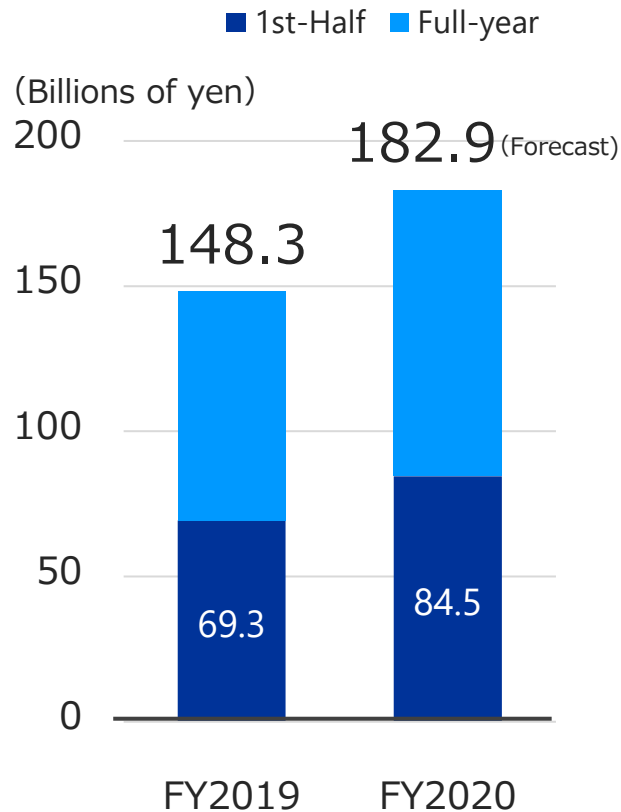
*3 Profit attributable to owners of parent

(Yen)

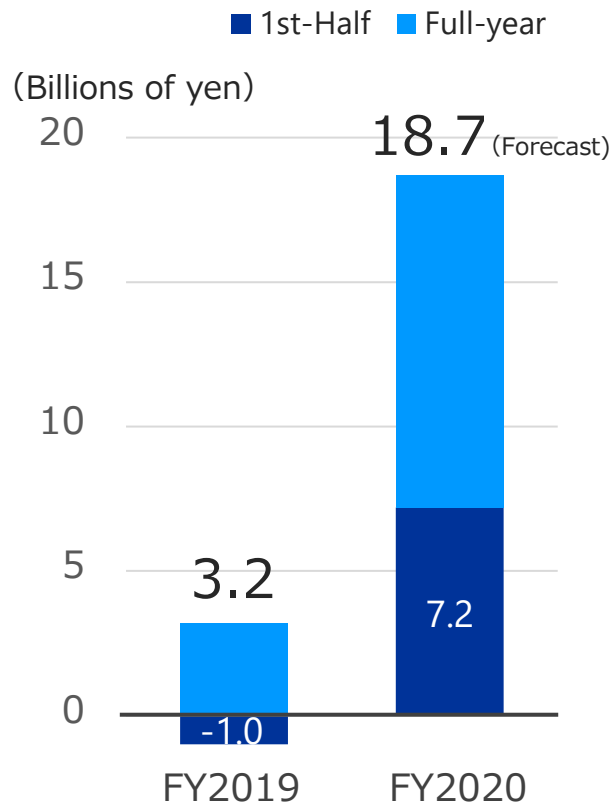
Cash Dividend per Share (Payout Ratio)	12.5 [Interim]	12.5 [Year-end]	25.0 (126%)	12.5 [Interim]	12.5 [Year-end]	25.0 (25%)
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Forecast of FY2020 (consolidated)

Net Sales

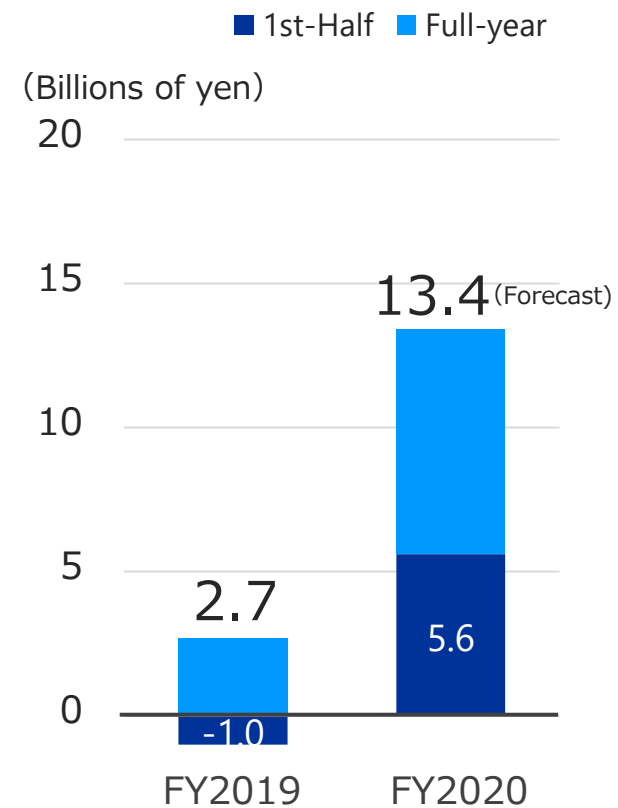


Operating Profit

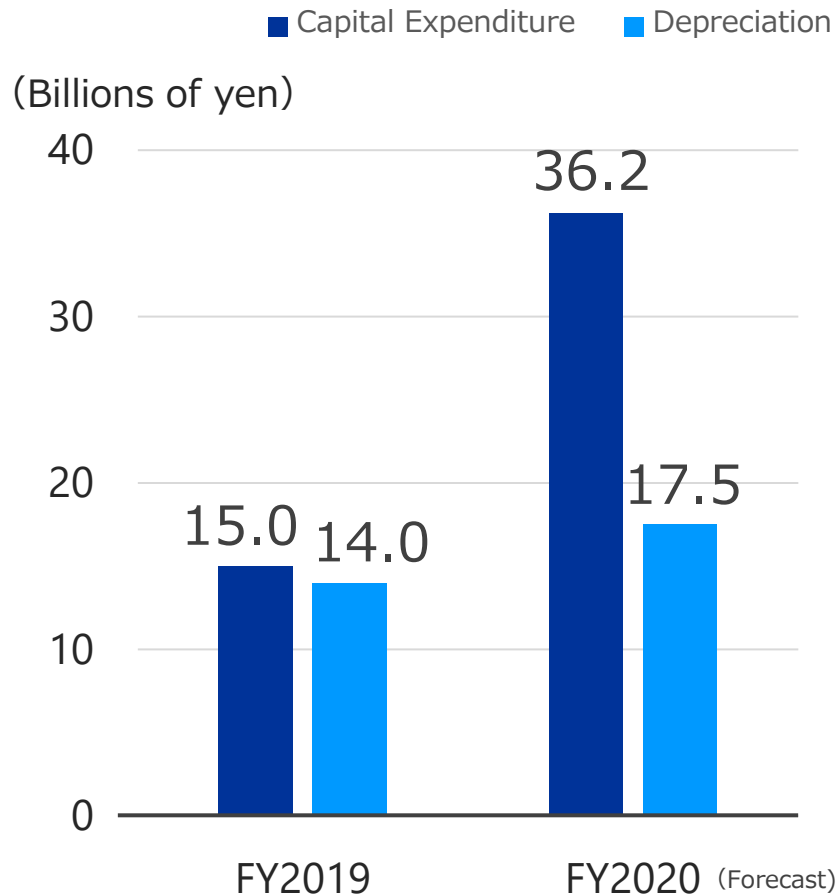


Profit*

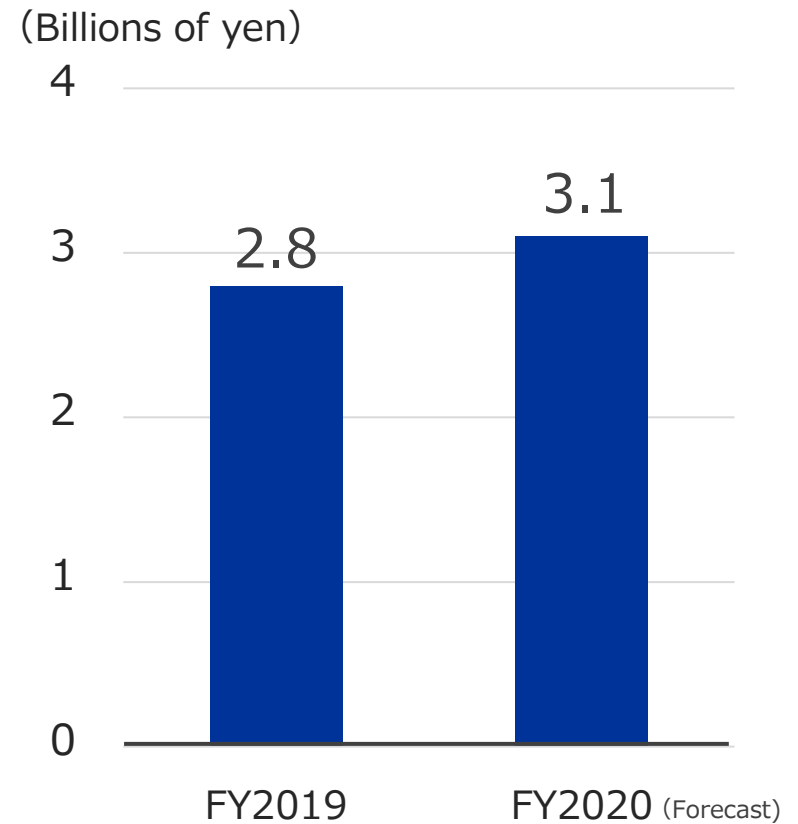
* Profit attributable to owners of parent



Capital Expenditure/ Depreciation



Research and Development



Notes to projected financial results:

The above projections were prepared based on estimates using information currently available. Actual results may differ from the projections. Also, many numerical values are shown in units of a billion yen as a general outline of business performance in this material. Because original values, which are managed in units of a million yen, are round off, the totals, difference, etc. shown in these materials may appear inaccurate. For assumptions and the other information regarding the projections, please refer to “the Financial Results” on IR library of our corporate website.